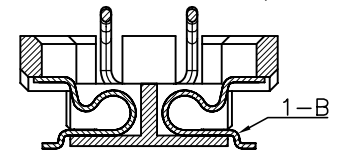
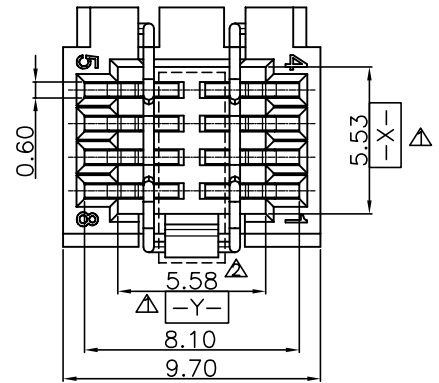
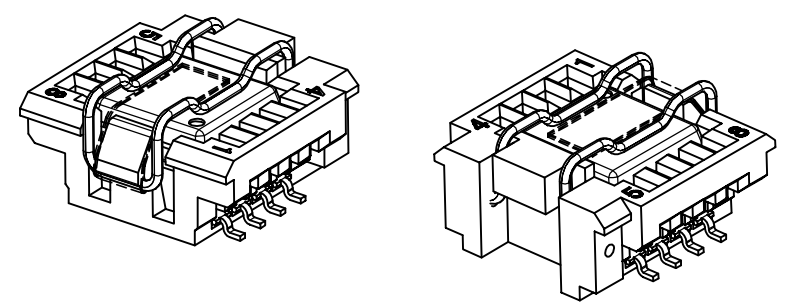
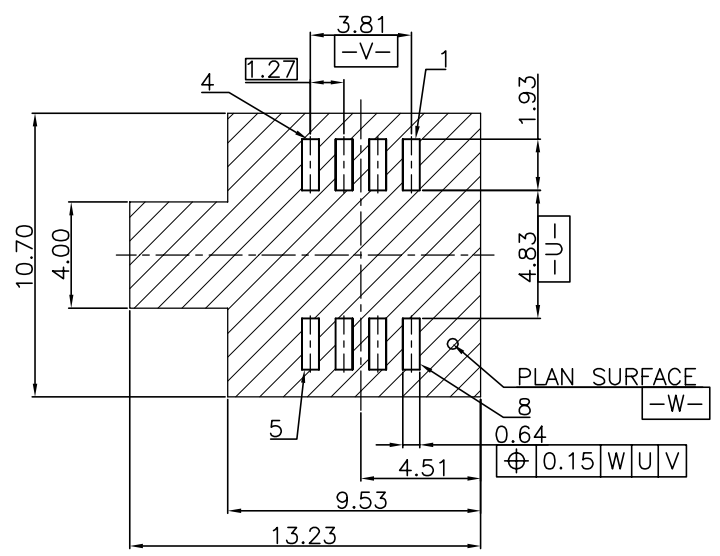


SPI FLASH SOCKET FOR SOIC 200mil CHIP

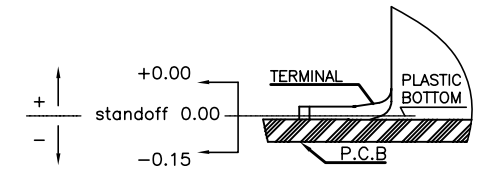
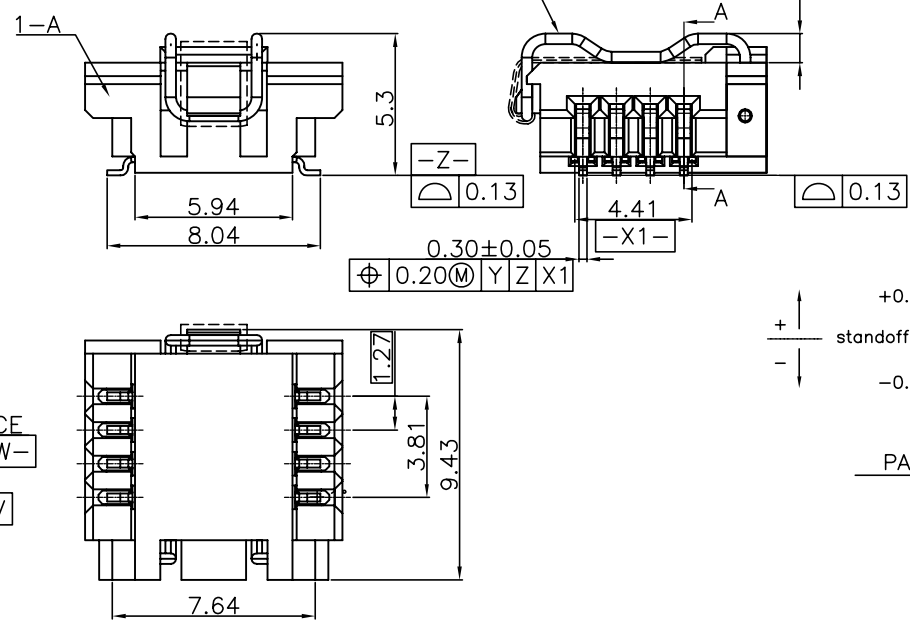
- NOTE:
- MATERIAL:
 - A. INSULATOR: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0
 - B. TERMINAL: COPPER ALLOY
 - C. COVER: STAINLESS STEEL WIRE
 - D. CAP: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0
 - PLATING: PURE TIN 100~200u", NICKEL UNDERPLATED
 - PART NUMBER: G6179-10 00 **
 - PLATING: 00=PURE TIN, 100~200u" 01=GOLD FLASH
 - PACKAGE: 00=TAPE AND REEL
 - PATENT NUMBER: Taiwan, ROC: M299953 Δ



SECTION A-A



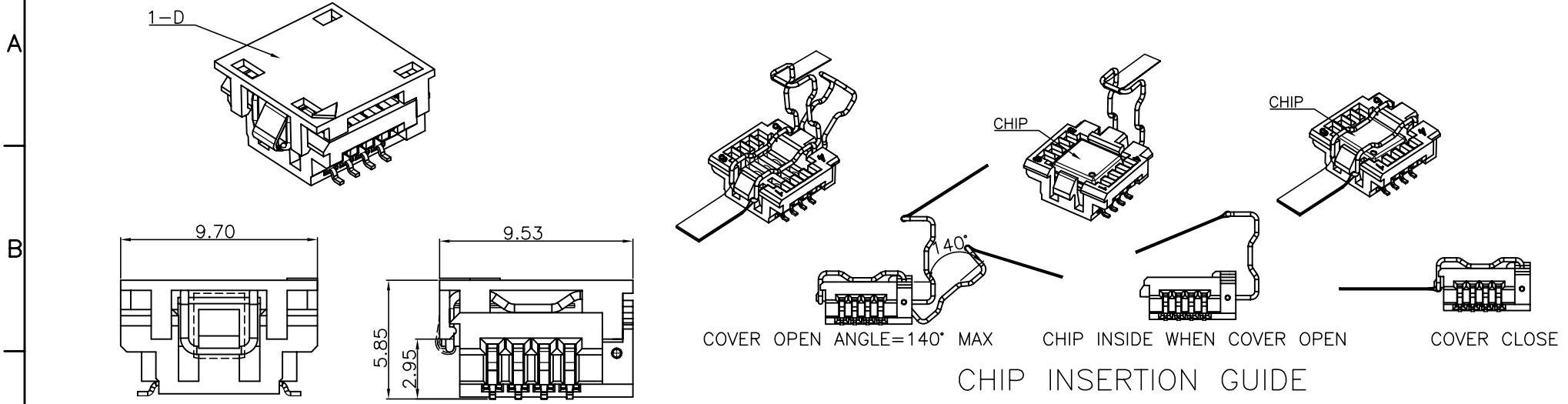
RECOMMENDED PCB LAYOUT TOP VIEW



PASTE P.C.B. SCHEMATIC

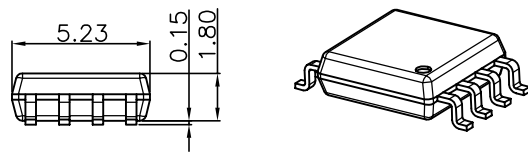
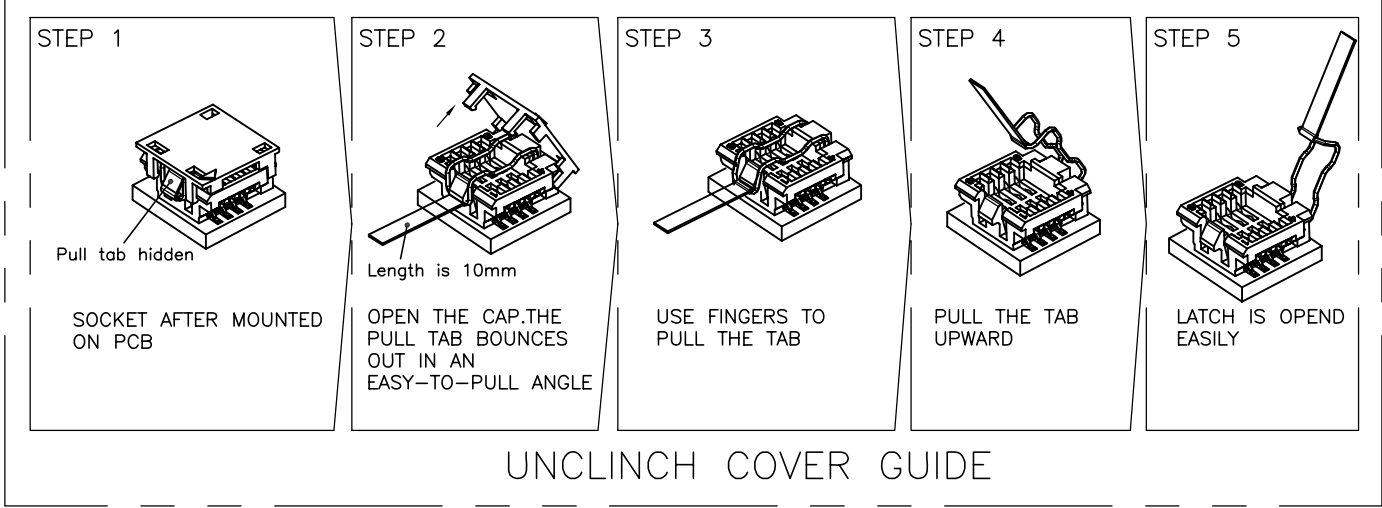
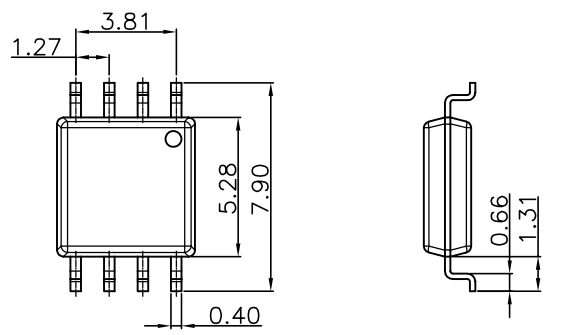
1 2 3 4

SPI FLASH SOCKET FOR SOIC 200mil CHIP



C

OUTLOOK DIMENSION WITH CAP



RECOMMENDED SOIC 200mil CHIP